# A generic CMOS-compatible platform for co-integrated plasmonics/photonics/ electronics PICs towards volume manufacturing of low energy, small size and high performance photonic devices

## D7.10 Press Release and Communication Kit

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| **Project acronym:** | **PLASMOFAB** |
| **Project title:** | A generic CMOS-compatible platform for co-integrated plasmonics/photonics/ electronics PICs towards volume manufacturing of low energy, small size and high performance photonic devices |
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| **Start date of the project:** | 01/01/2016 |
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# 1 Executive Summary

This deliverable provides a communication kit about the project (narrative text, photographs, slides and any other suitable communication material). The narrative text targets a general audience and focuses on the technical achievements as well as on the economical and societal benefits for the EU. Communications kit also includes, press releases for the launching of the project, website presentation and social accounts.

# 2 PLASMOfab narrative text (About PLASMOfab)

Photonic components constitute a major driving force of the European and global economies in a diverse range of technology sectors including ICT, medical, environmental, military and space applications with a total world market estimate of 30 Billion Euros. Despite this massive demand, **most photonic devices are large and bulky while in some cases they are assembled from discrete components of different underpinning technologies with very little automation**. In fact, most optical components are made either from III–V-based compounds such as indium phosphide (InP) and gallium arsenide (GaAs) or the electro-optic crystal lithium niobate ($LiNbO_3$). The net result is **fragmentation of development efforts, expensive optical devices and to make things worse, they cannot be effectively aggregated in large scale circuits** to address more complex functionalities at a low size and cost. To address those market needs, photonic integrated circuit (PIC) technologies have emerged as the means to realize mass production of photonics as an analogous to the production roadmap followed by the electronics industry for chips enclosed in mobile phones, tablets or other commercial electronic appliance.

In fact, it is no secret that the PIC industry, either targeting data communications, sensing or storage systems **will have to take advantage of the currently dominant and best-in-class processes of electronic CMOS manufacturing infrastructures** to decrease time-to-market and maximize return on investment. In such a scenario, the benefit of PIC technologies will be many-fold. In brief, PIC fabrication costs will follow economies of scale, dropping as the chip dimensions are decreasing and wafer revenues are increasing. In parallel CMOS friendly photonics based on silicon, silicon nitride or silicon dioxide will offer the CMOS foundries the business opportunity of monolithic integration of photonic components with supporting electronics using either front-end-of-line (FEOL) or back-end-of-line (BEOL) integration processes generating a highly rewarding business model. Consequently, **monolithic integration simplifies overall integration and packaging, increases density and enables tighter device-to-circuit proximity to decrease parasitics**. Nevertheless, despite the fact that silicon-related photonics match the basic electronic/photonics convergence criteria due to compatibility with CMOS materials and processes, significant incompatibilities still remain as potential barriers to the consolidation of photonics and electronics including dimensions, optical isolation or thermal budget.

Although thermal budget and optical isolation may in principle be addressed through special process flows **the issue of dimension mismatch between photonics and electronics still hampers the consolidation vision**. In fact, photonics do not require the fabrication of very small structures (critical dimensions of about 100 nm are typical) and devices are large when compared to transistors keeping the fabrication process of each chip separate although they may be destined to end up assembled back together. Eventually, **the decoupled development paths followed by electronics and photonics inevitably limit the manufacturability of complex PICs** that are being increasingly demanded by a disproportionally large market. Taking a step back, it becomes apparent that a key enabling technology is required as the intervention that will bridge those technological gaps and will bring photonics and electronics in a common integration platform. This new technology paradigm will eventually enable cost-effective, large-scale complex PICs with increased functional density and mass manufacturing by CMOS-based foundries.

Plasmonics have been proposed as a promising technology to exploit its metallic nature to mix with electronic contacts while offering unique functional advantages like enhanced light confinement and reduced device dimensions. A harmonic mixture of CMOS compatible plasmonic components with CMOS fabrication processes and photonics

technologies is expected to give the necessary push in plasmonics to demonstrate their clear advantages when selectively deployed in PICs. In a nutshell, when **the best of all three worlds of plasmonics, photonics and electronics converge in a single integration platform, PICs with unprecedented performances and functionalities will be realized** targeting diverse set of applications and industrial needs while mass production requirements will be met

PLASMOfab aims to address the ever increasing needs for low energy, small size, high complexity and high performance mass manufactured PICs by developing a revolutionary yet CMOS-compatible fabrication platform for seamless co-integration of active plasmonics with photonic and supporting electronic. The CMOS-compatible metals Aluminum, Titanium Nitride and Copper, will be thoroughly investigated towards establishing a pool of meaningful elementary plasmonic waveguides on co-planar photonic (Si, SiO2 and SiN) platforms along with the associated photonic-plasmonic interfaces. The functional advantages of PLASMOfab technology will be practically demonstrated by developing two novel functional prototypes with outstanding performances:

1) a compact, plasmonic bio-sensor for label-free inflammation markers detection with multichannel capabilities and record-high sensitivity by combining plasmonic sensors with electrical contacts, $Si_3N_4$ photonics, high-speed biofunctionalization techniques and microfluidics

2) a 100 Gb/s NRZ transmitter for datacom applications by consolidating low energy and low footprint plasmonic modulator and high-speed SiGe driving electronics in a single monolithic chip.

The new integration technology will be verified through wafer-scale fabrication of the prototypes at commercial CMOS fabs, demonstrating volume manufacturing and cost reduction capabilities. PLASMOfab technology will be supported by an EDA software design kit library paving the way for a standardized, fabless plasmonic/photonic IC eco-system.

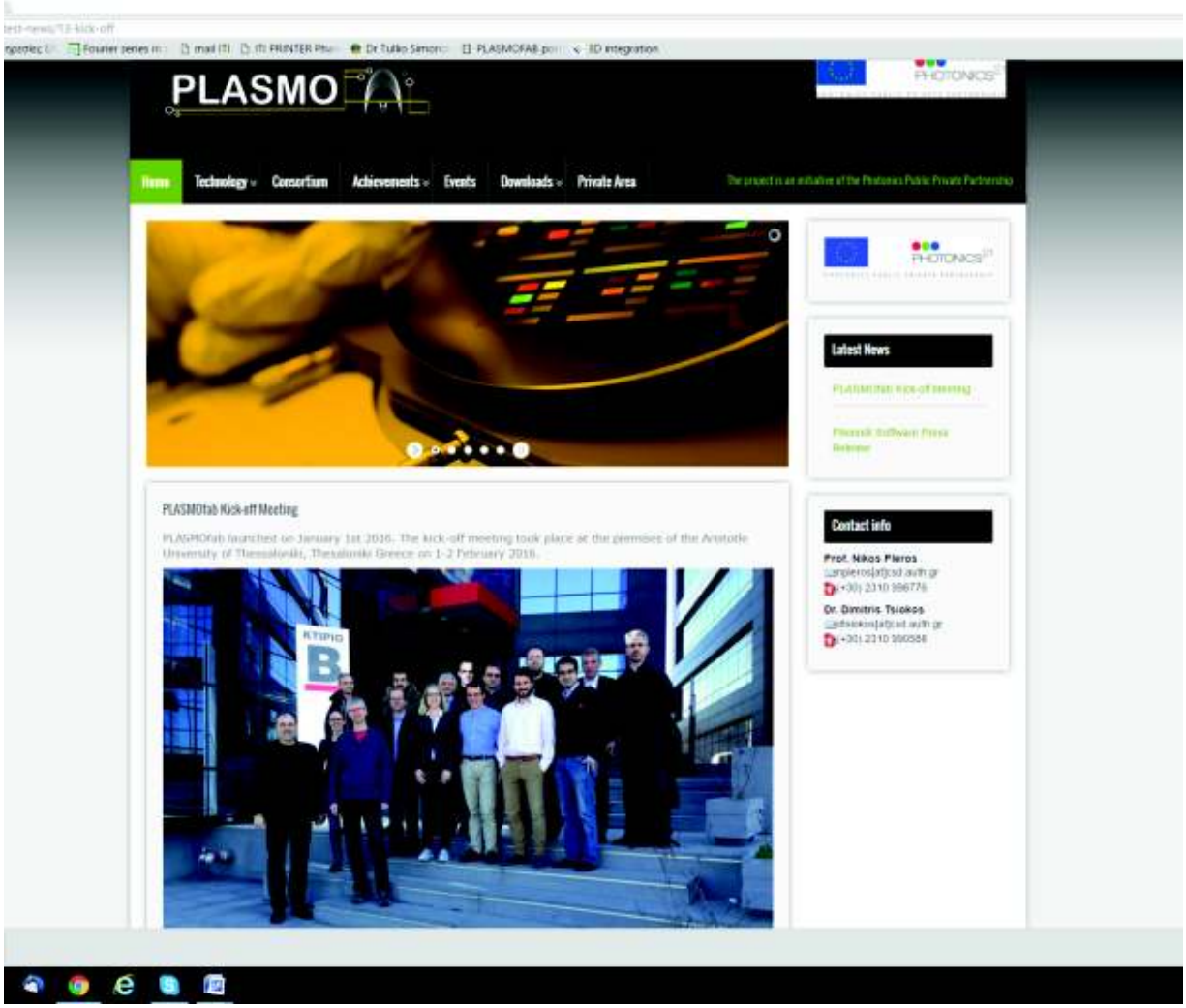
## PLASMOfab logo

The designed logo clearly captures the nature of PLASMOfab and provides an identity to the project. The logo has been designed from the beginning of the project and all partners felt that it successfully encapsulates the vision of PLASMOfab. The PLASMOfab logo has been designed to serve as the flag of PLASMOfab. It will be used at any public appearance and document.

The project brochure is under development and it is expected to

# 3 Kick-off meeting announcement and photos

The kick-off meeting of the project successfully took place at the premises of the Aristotle University of Thessaloniki in Greece 1-2 February 2016. The meeting was announced in the project official website along with consortium photos.



# 4 Press Release

A press release was published by PHX in order to communicate the beginning of the project. The press release was announced in the PHX website and linked in the project official webpage. see below).

http://www.phoenixbv.com/news.php?submenu=news&refID=7043

PhoeniX Software

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**PhoeniX Software works towards standardized Building Blocks to bridge the gap between photonics, plasmonics and electronic IC's**

**EU Project PLASMOfab was launched**

PLASMOfab is a new ambitious EU-HORIZON2020 project, that was launched on 1st January 2016 with the goal to develop the photonic integration technology (PIC) that will enable mass-manufacturing of high-performance photonic components. The three-year research project aims to revolutionalize integration technology of photonic devices by using plasmonic technology as the means to bridge the gap between photonic and electronic ICs. The project will focus on CMOS compatible metals and photonic structures that will be harmonically co-integrated with electronics via standardized CMOS processes. As a validation stage, the proposed PIC platform will be used along with advanced peripherals to develop predominant functional modules of unprecedented performances in the areas of optical data communications (low power, low footprint 100 Gb/s serial NRZ transmitter) and bio-sensing (Ultra-sensitive, multi-channel inflammation marker sensor).

The project is scheduled to run for three years bringing together 5 leading industrial partners and 5 top-ranked academic and research institutes in the PIC and opto-electronics value chain. Next to PhoeniX Software the project participants are the Aristotle University of Thessaloniki (Greece) also coordinating the project, Université de Bourgogne- member of UBFC (France), Swiss Federal Institute of Technology in Zurich (Switzerland), AMO GmbH (Germany), Austriamicrosystems AG (Austria), Micram Microelectronics GmbH (Germany), Saarland University (Germany), Mellanox (Israel) and Austrian Institute of Technology (Austria).

PLASMO PHOTONICS

Back to overview.

**Latest News**

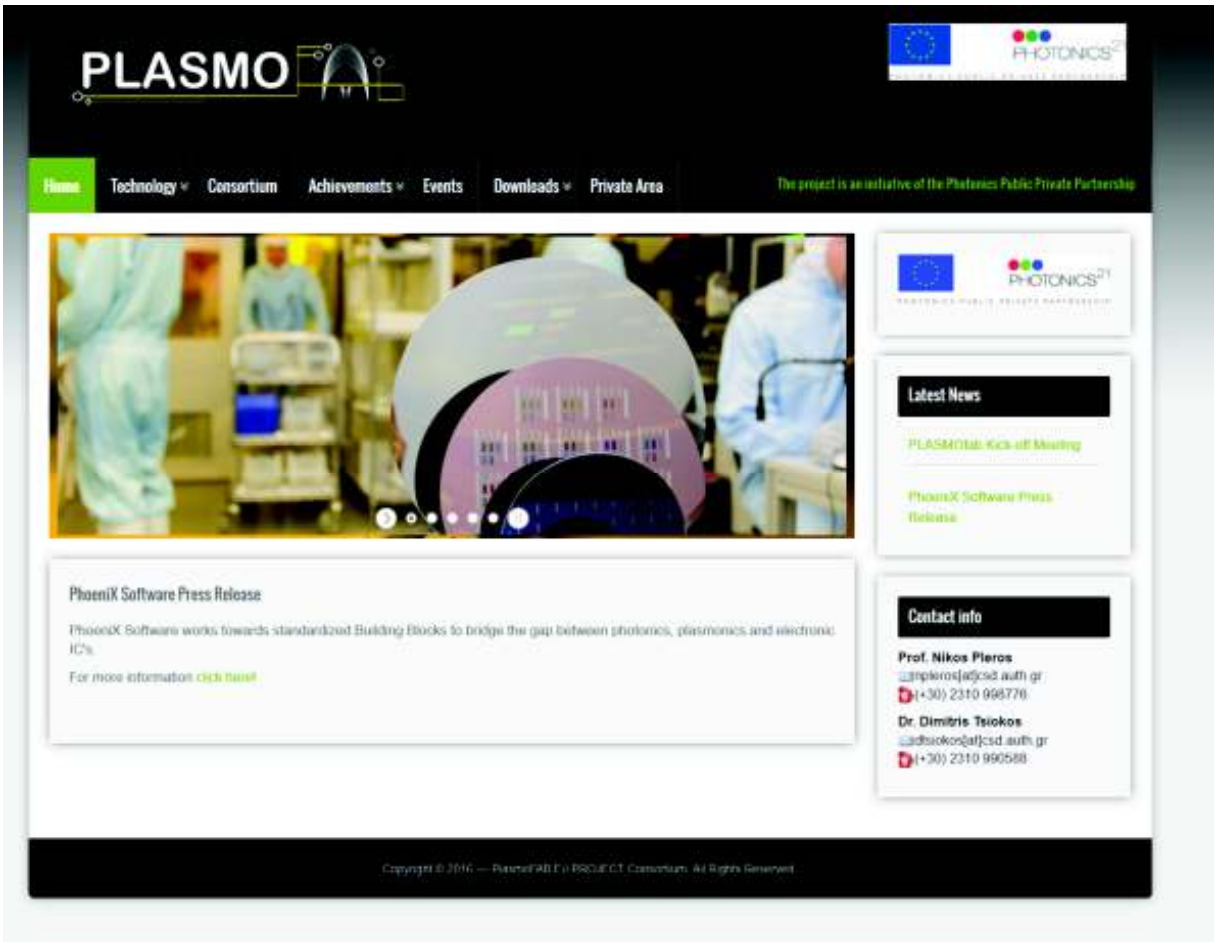
- PhoeniX Software and Sandia National Laboratories Collaborate to Advance Photonic Integrated Circuit Design and Manufacture
- PhoeniX Software works towards standardized Building Blocks to bridge the gap between photonics, plasmonics and electronic IC's
- PhoeniX Software is pleased to be speaking at the integrated photonic circuits industry's must attend global event
- Cadence announces collaboration with Lumerical and PhoeniX Software to offer a Virtuoso Based Design Flow for Electronic/Photonic ICs
- PhoeniX Software appoints Luster LightTech as distribution partner for China
- Wij zoeken een Teamleader Software development

**Events**

- Meet PhoeniX Software at UGM 2016
- Meet PhoeniX software at EIPBN
- PhoeniX Software will be at CDN Live, presenting the vision of the Virtuoso Platform-Based Design Flow for Electronic/Photonic ICs together with her partners Cadence and Lumerical
- ePIXfab Training Course on Silicon Photonics

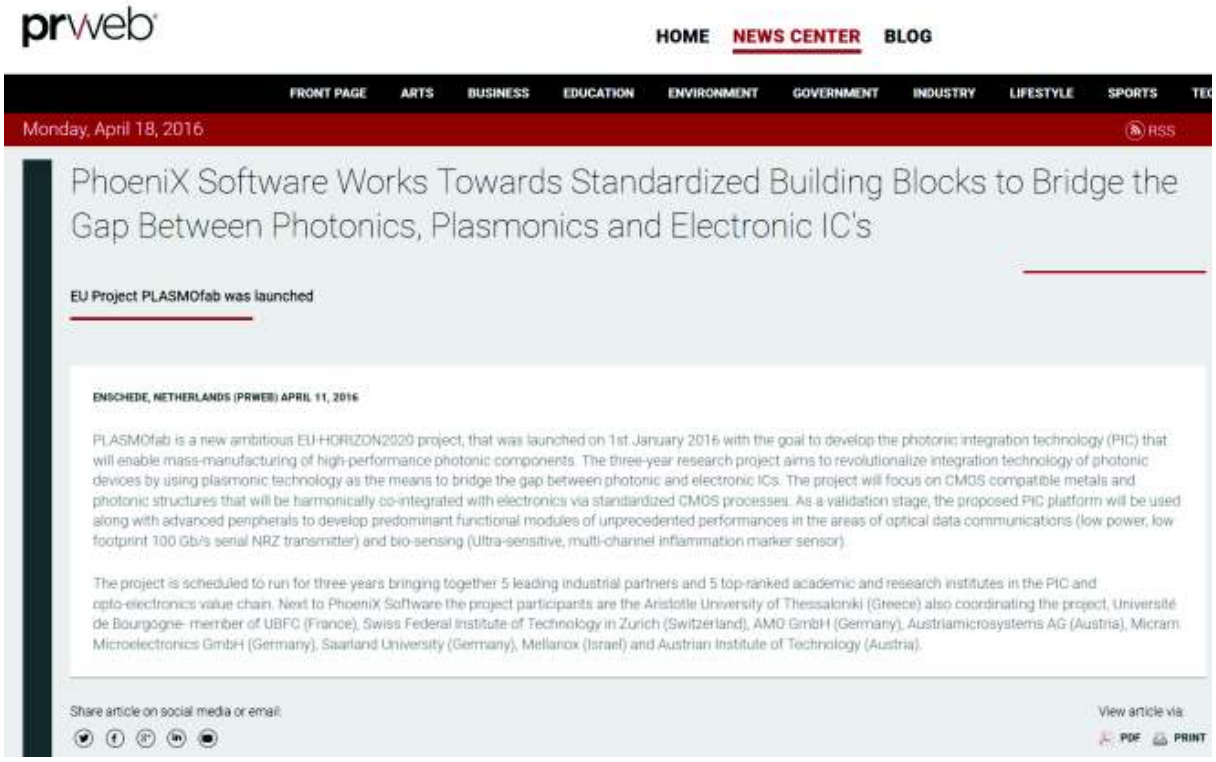
**In the Spotlight**

http://155.207.169.35/plasmofab/index.php/8-latest-news/14-phoenix-release




PLASMOfab was also announced by the following communication agents and third parties:

http://www.prweb.com/releases/2016/04/prweb13324166.htm



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Monday, April 18, 2016 RSS

# PhoeniX Software Works Towards Standardized Building Blocks to Bridge the Gap Between Photonics, Plasmonics and Electronic IC's

## EU Project PLASMOfab was launched

ENSCHEDE, NETHERLANDS (PRWEB) APRIL 11, 2016

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03-21-2016 10:43 AM CET - Science & Education



**PhoeniX Software works towards standardized Building Blocks to bridge the gap between photonics, plasmonics and electronic IC's**

Press release from: PhoeniX Software



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Pioneering photonics design automation already since 1991, today PhoeniX Software has a global presence and is a trusted and well recognized partner for a large number of organizations.

We enable easy and cost-effective realization of integrated photonics chips and systems, by means of our internally developed superior products and services. Our customers range from large OEM's to start-ups and include some of the world's top universities and research institutes.

As the leader in Photonic IC design solutions, we will continue to develop the market by anticipating market demand and customer needs. In combination with our strategic partnerships, this results in offering world class design flows and access to all relevant fabrication technologies for our customers.

P.O. Box 545
7500 AM Enschede
the Netherlands
www.phoenixbv.com

*This release was published on openPR.*

http://m.mysanantonio.com/business/press-releases/article/PhoeniX-Software-Works-Towards-Standardized-7240404.php

PhoeniX Software Works Towards Standardized Building Blocks to Bridge the Gap Between Photonics, Plasmonics and Electronic ICs

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# PhoeniX Software Works Towards Standardized Building Blocks to Bridge the Gap Between Photonics, Plasmonics and Electronic IC's

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EU Project PLASMOfab was launched

Enschede, Netherlands (PRWEB) April 11, 2016

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PRWeb Monday, April 11th 2016

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For the original version on PRWeb visit: http://www.prweb.com/releases/2016/04/prweb13324166.htm

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# 5 Brochure

A brochure has been generated for illustrative dissemination of the PLASMOfab in meetings, workshops, conferences, exhibitions and open public events. The brochure visualizes in an easy and acceptable fashion the project goals and expected outcomes along with the project factsheet. The brochure will be distributed to all members of the consortium for further communication of the project. The brochure is shown below.

**Brochure Cover**


**Brochure Inside**

# 6 PLASMOfab Web-site

The PLASMOfab Web Site incorporates a structure ready to host all current and progressively developed information of the project. A special section for secure access to the project's restricted area for internal data sharing and workflow is available.

WWW offers a wide range of possibilities for the dissemination of PLASMOfab. For this reason, the project website has been developed and will be maintained by making information related to PLASMOfab available to the wide audience for dissemination of the project. It is intended to provide an overview of the project goals, an introduction to the PLASMOfab consortium, and a gateway for discussing PLASMOfab -related issues. The PLASMOfab web site is considered as one of the most effective dissemination channel, as it is global and can be accessed anytime from any interested party. The PLASMOfab web site offers general information on the project, such as its rationale, the project progress, expected results and partners. Since it serves as a promotional tool, it will be enriched during the project with attractive info of expected benefits, related reference information (e.g. studies, news, papers) and access to other promotional material such as brochure and poster.

The PLASMOfab web site contains the project identity (logo, colour scheme, etc.) developed as part of the WP7 work and has been designed in order to provide both the general public and the project partners with useful information concerning PLASMOfab.

The idea behind the site is twofold. Firstly, to provide a point of reference for people interested in learning more about the project (with information such as PLASMOfab objectives, the expected benefits, participating partners, etc.) and secondly as a place from which to distribute documents and information addressed strictly to the partners. For this to happen the overall PLASMOfab site is divided to two sectors, one for the public and another for authorized only users.

The PLASMOfab project Web site can be found at the address: http://www.plasmofab.eu/

In the picture below, we present the main menu of the site and the sub-menus of each category.


The structure of the web site is quite standard and at the onset of its operation contains the following basic sections:

- Home page, which is the main page of the website and shows its structure.
- Technology, which includes two submenus:
  - Concept which provides a general overview of the project.
  - Objectives which provides a main description of each of the project's objectives.
- Consortium, which lists the PLASMOfab's consortium members.
- Achievements, which includes three submenus:
  - Publications, which contains all the journal and conferences publications carried out within PLASMOfab.
  - Devices & Prototypes, which will contain all non-confidential information regarding the devices and prototypes that will result from the project.
- Events: This menu will provide information to users regarding events that will take place within the project.
- Downloads which includes three submenus:
  - Factsheet: This submenu provides some information regarding the project and the user can download the PLASMOfab presentation document.
  - Press Releases, which will contain newsworthy announcements regarding the project.
  - Public Report: In this submenu we will publish all non-confidential reports/newsletters regarding the milestones that we have achieve within PLASMOfab projects.
- Private Area which provides the link towards the private area accessible only by the consortium's member. The main menu tab "Private Area" redirects the user to the safe share point portal of "Austrian Institute of Technology". This is an advanced data sharing and project management platform which was provided by AIT for the use of

PLASMOfab. Each partner received individual login credentials for accessing and using the platform.

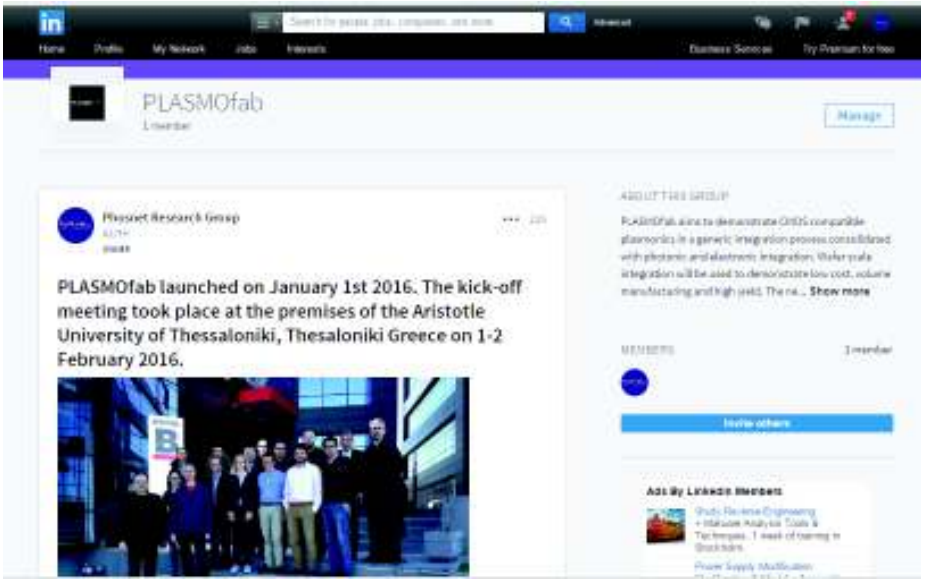
# 7 PLASMOfab Social Media Accounts

Three social media accounts have been already established in order to promote further the PLASMOfab project. These three accounts will be maintained by making information related to PLASMOfab available to the wide audience for dissemination of the project.

- Facebook Account: "PLASMOfab"


- Twitter Account: "PLASMOfab"

- LinkedIN Account: "PLASMOfab Project"



# 8 Summary

This deliverable provides a communication kit with all communication tools that are deployed in PLASMOfab. Specifically the report presents the following communication tools generated for the project:

- Project narrative
- Project logo.
- Press Releases
- Project brochure
- Project web site
- Project social media accounts.